

Features

- Trench LV MOSFET Tenchnology
- High Density Cell Design For Ultra Low R_{DS(on)}
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note1)
- · Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

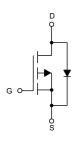
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 50°C/W Junction to Ambient^(Note2)
- Thermal Resistance: 1.4°C/W Junction to Case

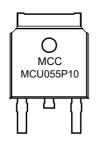
Parameter		Symbol	Rating	Unit	
Drain-Source Voltage		V _{DS}	-100	V	
Gate-Source Volltage		V _{GS}	±20	V	
Continuous Drain Current	T _C =25°C		-28	Α	
	T _C =100°C	l _D	-17		
Pulsed Drain Current (Note3)		I _{DM}	-112	Α	
Total Power Dissipation ^(Note4)		P _D	89	W	
Single Pulse Avalanche Energy (Note 5)		E _{AS}	118	mJ	

Note:

- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of $R_{\theta JA}$ is measured with the device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. P_{D} is based on max. junction temperature, using junction-case thermal resistance.
- 5. T_J =25°C, V_{DD} =-50V, V_{GS} =-10V, R_G =25 Ω , L=0.5mH.

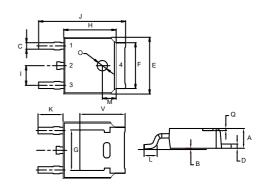
=bhYfbU GHi Wi fY UbX A Uf_]b[7 cXY





P-CHANNEL MOSFET

DPAK(TO-252)



- Gate
- 2,4. Drain
 - 3. Source

	DIMENSIONS				
DIM	INC	INCHES		М	NOTE
DIIVI	MIN	MAX	MIN	MAX	NOTE
Α	0.087	0.094	2.20	2.40	
В	0.000	0.005	0.00	0.13	
С	0.026	0.034	0.66	0.86	
D	0.018	0.023	0.46	0.58	
Е	0.256	0.264	6.50	6.70	
F	0.201	0.215	5.10	5.46	
G	0.190		4.83		TYP.
Н	0.236	0.244	6.00	6.20	
I	0.086	0.094	2.18	2.39	
J	0.386	0.409	9.80	10.40	
K	0.114		2.90		TYP.
L	0.055	0.067	1.40	1.70	
М	0.063		1.60		TYP.
0	0.043	0.051	1.10	1.30	
Q	0.000	0.012	0.00	0.30	
V	0.211		5.35		TYP.



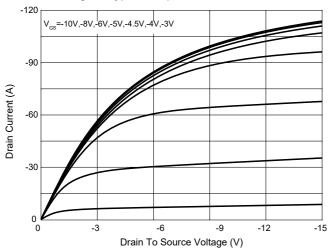
Electrical Characteristics @ 25°C (Unless Otherwise Specified)

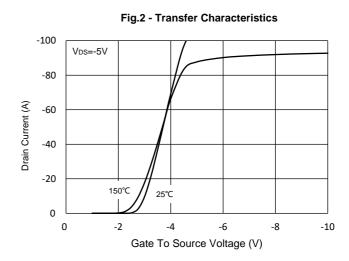
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static Characteristics	1			1	I		
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250μA	-100			V	
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-100V, V _{GS} =0V			1	μA	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=-250\mu A$	-1.5	-2	-2.5	V	
Drain-Source On-Resistance	Б	V _{GS} =-10V, I _D =-20A	42 55		55	0	
	R _{DS(on)}	V _{GS} =-4.5V, I _D =-15A		46	64	mΩ	
Gate Resistance	R _g	f=1 MHz, Open drain		6		Ω	
Diode Characteristics							
Continuous Body Diode Current	Is				-28	Α	
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-20A			-1.2	V	
Reverse Recovery Time	t _{rr}	1 - 004 -11/-141004/		32		ns	
Reverse Recovery Charge	Q _{rr}	I _F =-20A, dI/dt=100A/μs		47		nC	
Dynamic Characteristics			·				
Input Capacitance	C _{iss}			3480			
Output Capacitance	C _{oss}	V_{DS} =-50V, V_{GS} =0V,f=1MHz		145		pF	
Reverse Transfer Capacitance	C _{rss}			118		1	
Total Gate Charge	Q_g			71			
Gate-Source Charge	Q_{gs}	V_{DS} =-50V, V_{GS} =-10V, I_{D} =-20A		11		nC	
Gate-Drain Charge	Q_{gd}			17			
Turn-On Delay Time	t _{d(on)}			13			
Turn-On Rise Time	t _r	V _{DD} =-50V, V _{GS} =-10V,		24		no	
Turn-Off Delay Time	$t_{d(off)}$	$R_G=3\Omega, I_D=-20A$		120		- ns	
Turn-Off Fall Time	t _f			61			



Curve Characteristics

Fig. 1 - Typical Output Characteristics





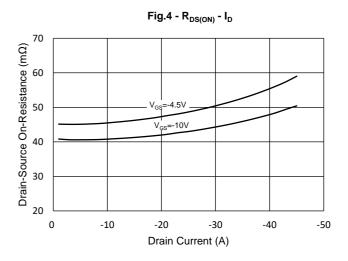
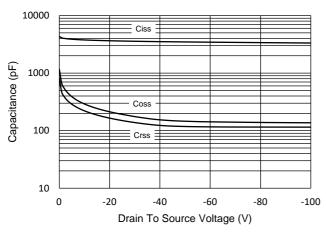
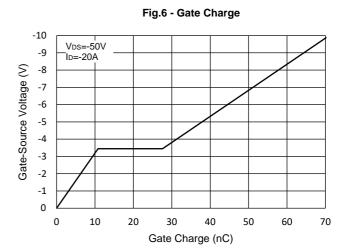


Fig.5 - Capacitance Characteristics

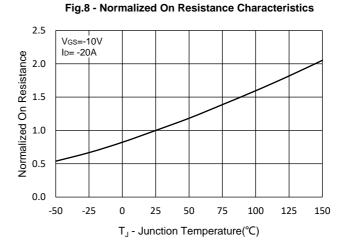
Gate To Source Voltage (V)

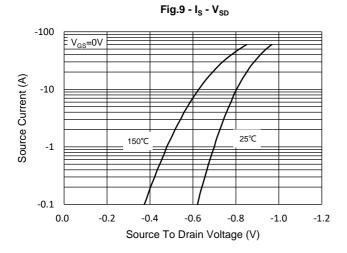


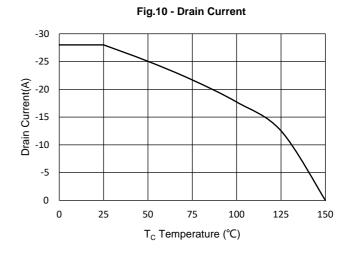


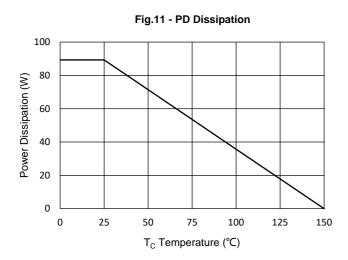


Curve Characteristics











Curve Characteristics



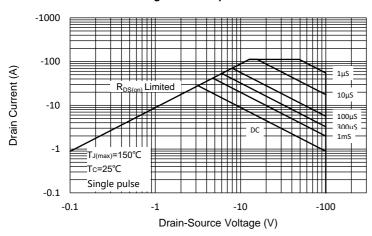
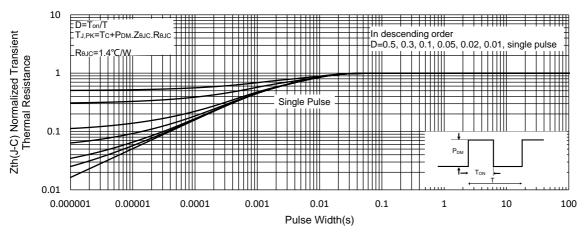


Fig.13 - Normalized Transient Thermal Impedance





Ordering Information

Device	Packing	
Part Number-TP	Tape&Reel: 2.5Kpcs/Reel	

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